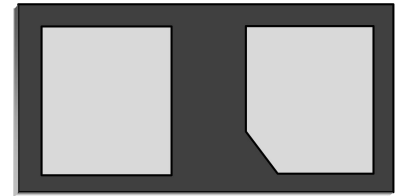


Features

- 100 Watts Peak Pulse Power per Line ($t_p = 8/20\mu s$)
- Small Body Outline Dimensions
- Protects one I/O or Power Line
- Low Clamping Voltage
- Working Voltage: 5V
- Low Leakage Current

**DFN0603-2L**

IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 10A (8/20 μs)

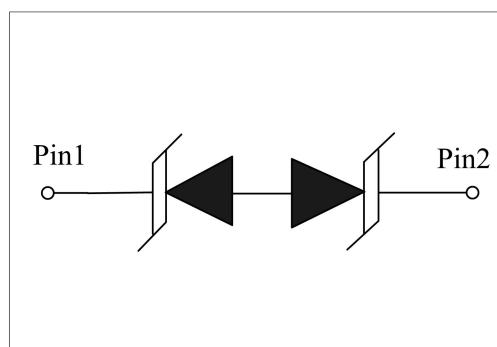
Mechanical Characteristics

- DFN0603-2L package
- Marking : Marking Code
- Packaging: Tape and Reel per EIA 481
- RoHS Compliant & HF

Applications

- Laptop Computers
- Cellular Phones
- Digital Cameras
- Personal Digital Assistants (PDAs)

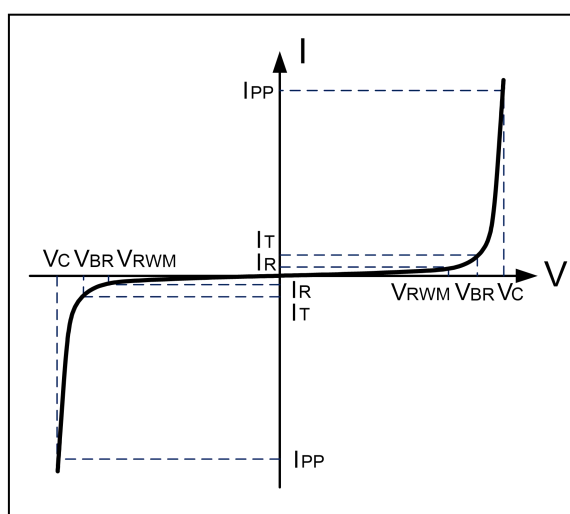
Schematic & PIN Configuration



Absolute Maximum Rating			
Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	100	W
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	10	A
Operating Temperature	T_J	-55 to + 125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Parameters

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current



Electrical Characteristics(T=25°C unless otherwise noted)

ES05DMS-BH						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				5	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	5.6			V
Reverse Leakage Current	I_R	$V_{RWM}=5V$			100	nA
Clamping Voltage	V_C	$I_{PP}=10A, t_p=8/20\mu s$		8	10	V
Dynamic Resistance ^{1,2}	R_{DYN}	$TLP=0.2/100ns$		0.2		Ω
ESD Clamping Voltage ¹	V_C	$I_{PP} = 4A, t_p = 0.2/100ns (TLP)$		5.9		V
ESD Clamping Voltage ¹	V_C	$I_{PP} = 16A, t_p = 0.2/100ns (TLP)$		7.7		V
Junction Capacitance	C_j	$V_R=0V, f=1MHz$			20	pF

Notes : 1、TLP Setting : $t_p=100ns, t_r=0.2ns, I_{TLP}$ and V_{TLP} sample window: $t_1=70ns$ to $t_2=90ns$.

2、Dynamic resistance calculated from $I_{PP}=4A$ to $I_{PP}=16A$ using "Best Fit".

Typical Characteristics

Figure 1: Peak Pulse Power Vs Pulse Time

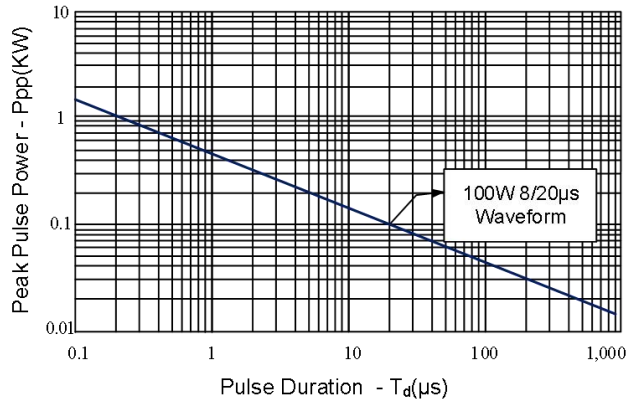


Figure 2: Power Derating Curve

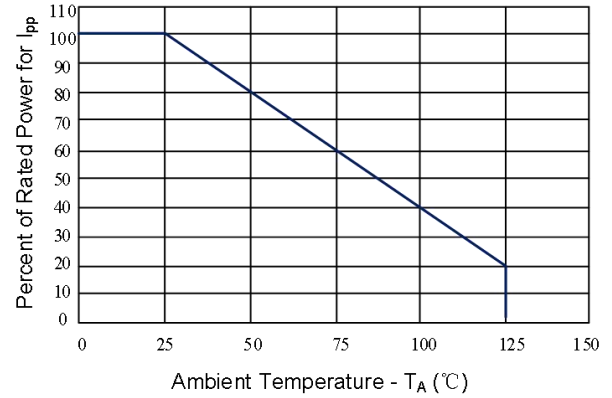


Figure 3: Clamping Voltage vs. Peak Pulse Current

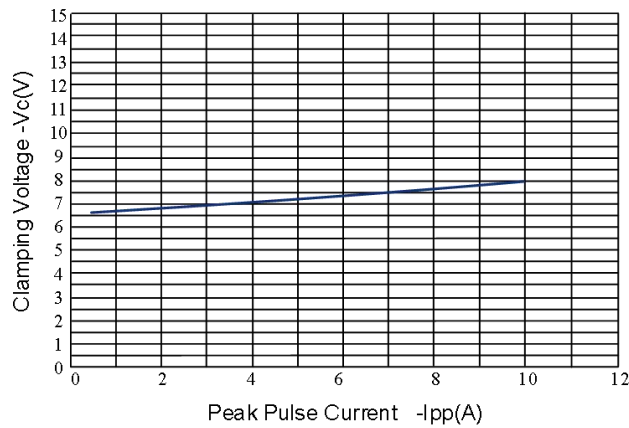


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

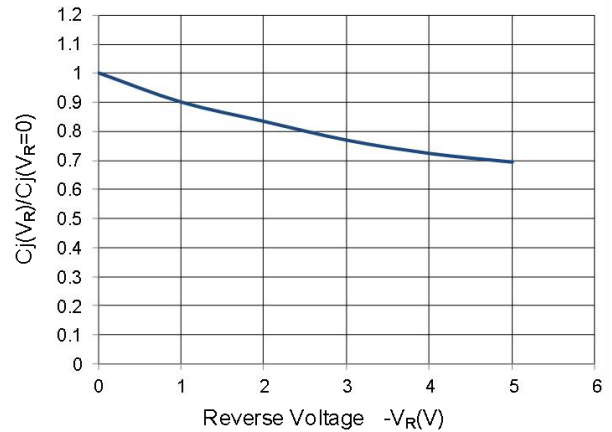


Figure 5: TLP Positive I-V Curve

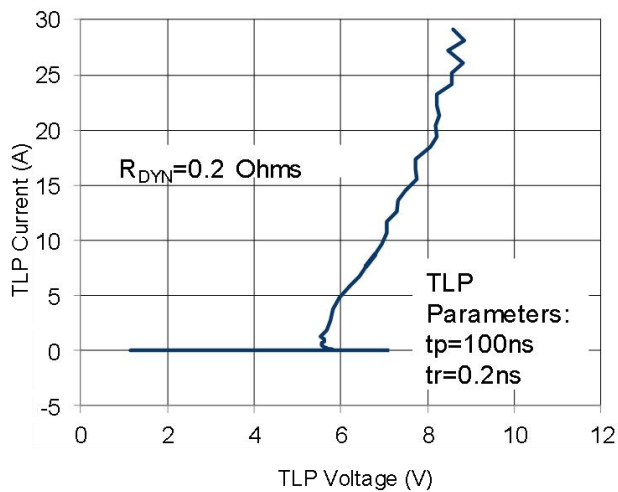
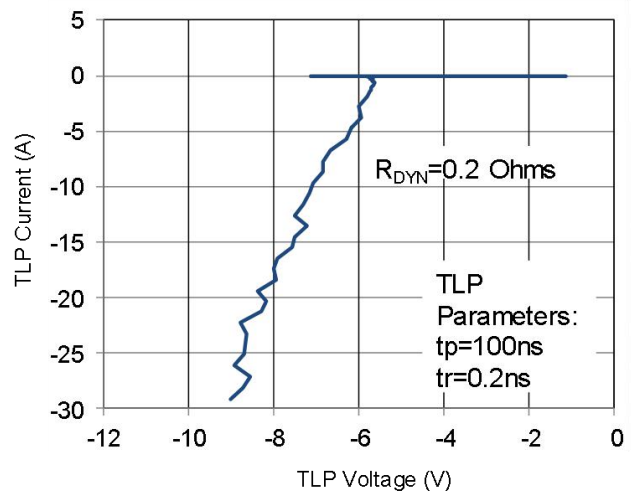
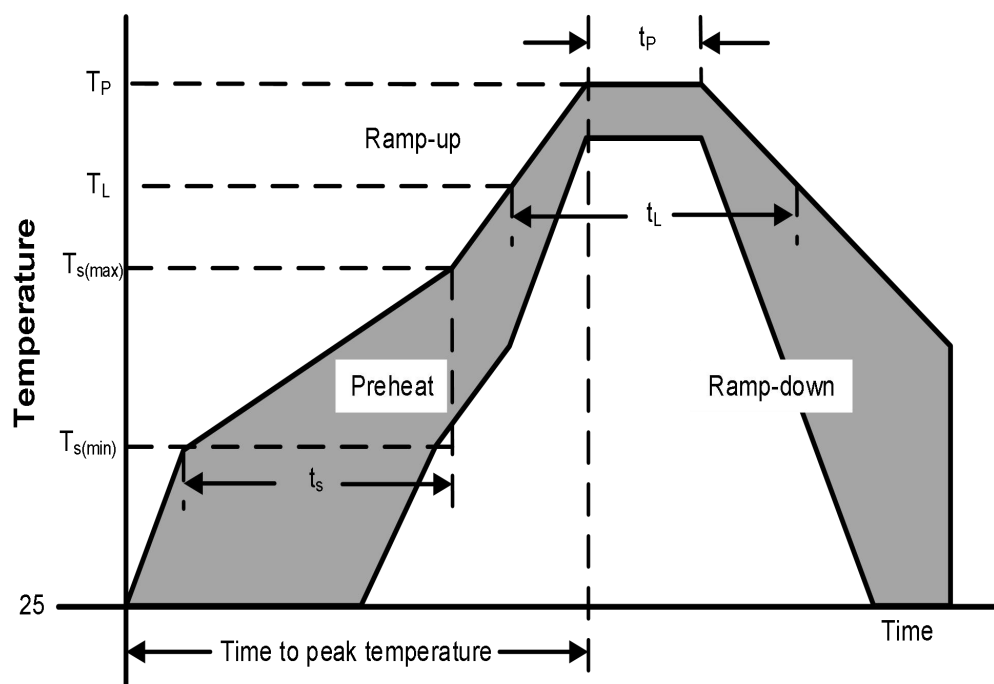


Figure 6: TLP Negative I-V Curve



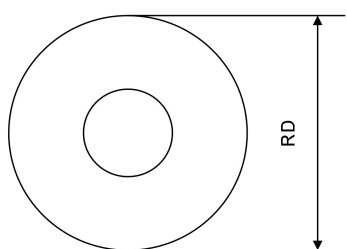
Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{s(max)}$ to T_L —Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C

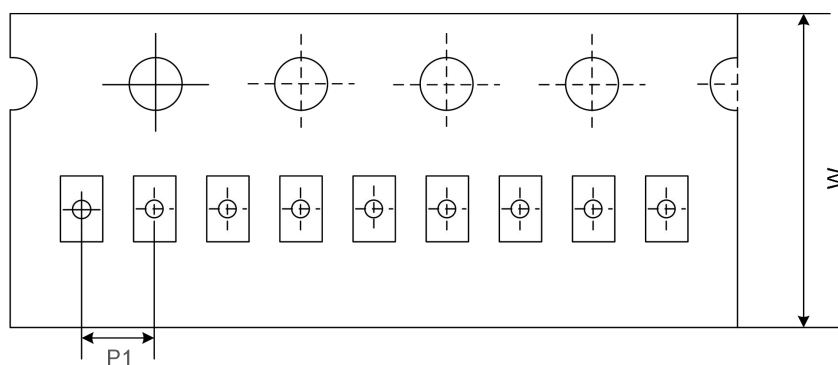


TAPE AND REEL INFORMATION

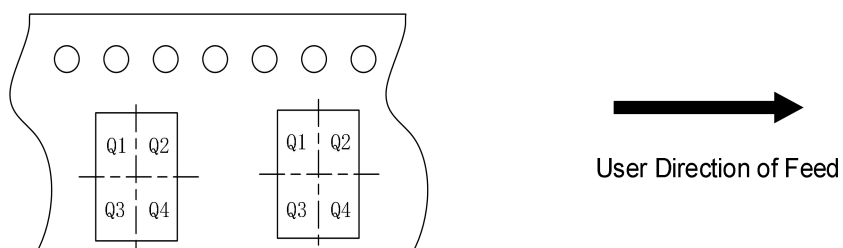
Reel Dimensions



Tape Dimensions

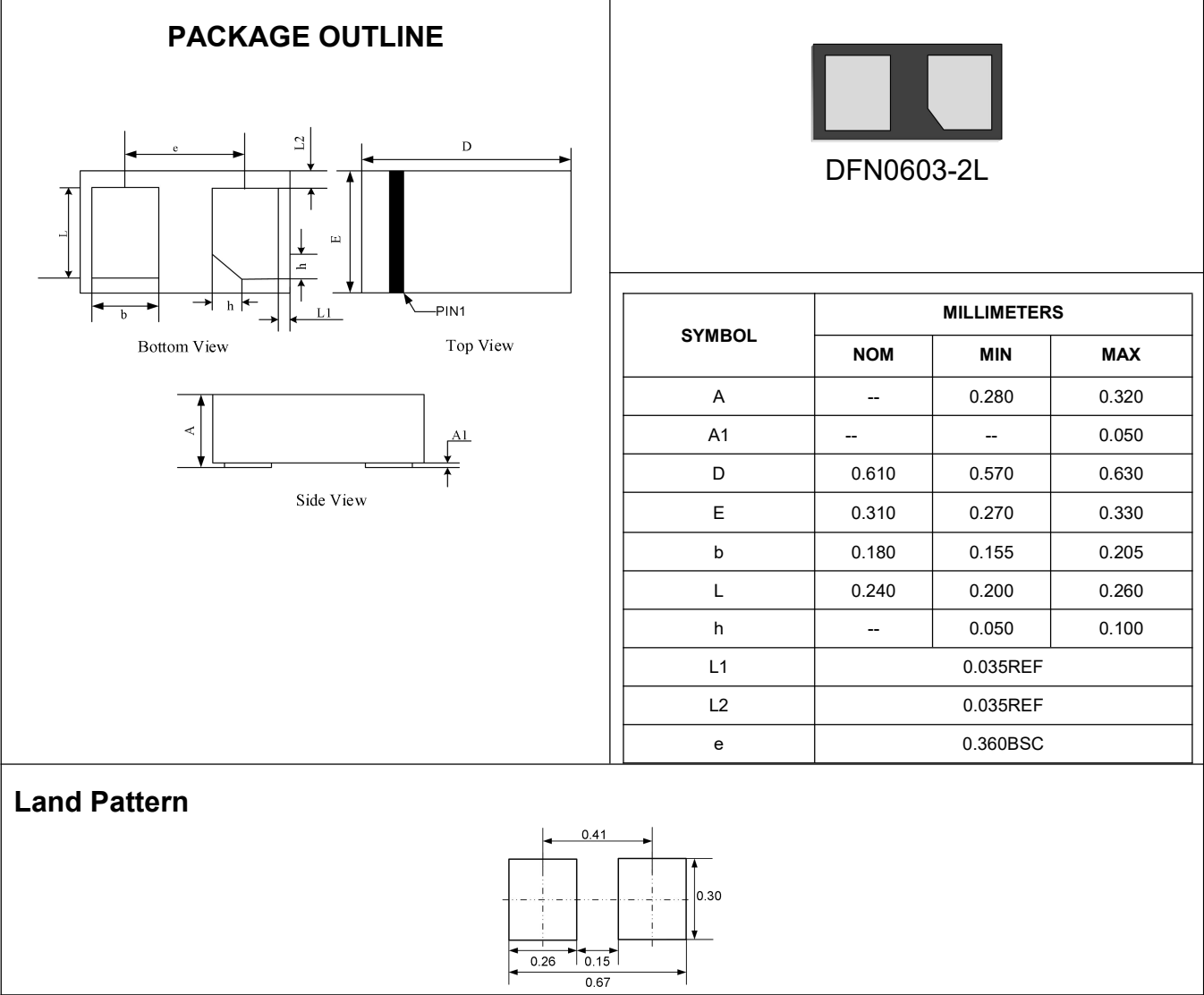


Quadrant Assignments For PIN1 Orientation In Tape



RD	Reel Dimensions	7 inch
W	Overall width of the carrier tape	8 mm
P1	Pitch between successive cavity centers	2mm
Pin1	Pin1 Quadrant	Q1 Q2

Outline Drawing –DFN0603-2L



Marking Codes

Part Number	Marking Code
ES05DMS-BH	PIN 1 A = Specific Device Code M = Month Code

Package Information

Qty: 15k/Reel